

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	0	((chip die (semiconductor near (device element component))) with (substrate carrier board pcb) with (adhesive (bonding near (material layer tape))) with (second near (polymer polymeric polyimide)) with ((circuit near layer) (conductive near (trace pattern))) with ((copper cu) near1 electroplating) with ((passive near (element device)) resistor capacitor inductor waveguide filter) with (bump ball) with (cutting singulating sawing dicing)).dlm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/ 03/ 28 00:56
L3	0	((chip die (semiconductor near (device element component))) same (substrate carrier board pcb) same (adhesive (bonding near (material layer tape))) same (second near (polymer polymeric polyimide)) same ((circuit near layer) (conductive near (trace pattern))) same ((copper cu) near1 electroplating) same ((passive near (element device)) resistor capacitor inductor waveguide filter) same (bump ball) same (cutting singulating sawing dicing)).dlm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/ 03/ 28 00:58

L4	0	((chip die (semiconductor near (device element component))) and (substrate carrier board pcb) and (adhesive (bonding near (material layer tape))) and (second near (polymer polymeric polyimide)) and ((circuit near layer) (conductive near (trace pattern))) and ((copper cu) near1 electroplating) and ((passive near (element device)) resistor capacitor inductor waveguide filter) and (bump ball) and (cutting singulating sawing dicing)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 00:59
L5	0	((chip die (semiconductor near (device element component))) and (substrate carrier board pcb) and (adhesive (bonding near (material layer tape))) and (second near (polymer polymeric polyimide)) and ((circuit near layer) (conductive near (trace pattern))) and ((copper cu) near1 electroplating) and ((passive near (element device)) resistor capacitor inductor waveguide filter) and (bump ball) and (cutting singulating sawing dicing))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 00:59

L6	629406	"257"/\$.ccls. "438"/\$.ccls. "361"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 01:00
L7	77	6 and (chip die (semiconductor near (device element component))) and (substrate carrier board pcb) and (adhesive (bonding near (material layer tape))) and ((polymer polymeric polyimide) near layer) and ((circuit near layer) (conductive near (trace pattern))) and (copper cu) and electroplating and ((passive near (element device)) resistor capacitor inductor waveguide filter) and (bump ball) and (cutting singulating sawing dicing)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 01:02
L8	44	6 and (chip die (semiconductor near (device element component))) and (substrate carrier board pcb) and (adhesive (bonding near (material layer tape))) and ((polymer polymeric polyimide) near layer) and ((circuit near layer) (conductive near (trace pattern))) and ((copper cu) with electroplating) and ((passive near (element device)) resistor capacitor inductor waveguide filter) and (bump ball) and (cutting singulating sawing dicing)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 01:03

3/28/2008 1:05:15 AM

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